

Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

| Supplier | | User Part Number | | | | |
|---------------------------|--|-----------------------------------|-----------|------------|-----------|--|
| Nexperia B.V. | | PMEG6002ELD-Q | | | | |
| Name of Laboratory | | Part Description | | | | |
| Assembly reliability labs | | Nexperia DHAM | | Schottky | | |
| | | MCD package | | | | |
| Based on AEC-Q101 Test | Test Conditions | Duration | # Lots | # Quantity | # Rejects | |
| # E1 | TEST Pre- and Post-Stress Electrical Test Tamb = 25 °C | N/A | see below | all parts | see below | |
| # A1 | PC Preconditioning JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85% Reflow soldering | 24 hours 168 hours 3 cycles | 208 | 9760 | 0 | |
| # B1 | HTRB High Temperature Reverse Bias MIL-STD-750-1 M1038 Method A Tj = Tjmax, Vr = 100% of max. datasheet reverse voltage ^[1] | 1000 hours | 206 | 9320 | 0 | |
| # A4 | TC Temperature Cycling JESD22-A104 -65 °C to Tjmax, not to exceed 150°C | 1000 cycles | 53 | 2400 | 0 | |
| # A3 or | UHAST Unbiased HAST JESD22-A118 Tamb = 130 °C, RH = 85 % | 96 hours | 53 | 2400 | 0 | |
| # A3 alt | AC Autoclave JESD22-A102 Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia) | | | | | |
| # A2 alt | H3TRB High Humidity High Temperature Reverse Bias JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage ^{[1], [2]} | 1000 hours | 53 | 2400 | 0 | |
| # A5 | IOL Intermittent Operating Life MIL-STD-750 Method 1037 ton = toff, devices powered to insure ΔTj = 100 °C for 15000 cycles | 1000 hours | 49 | 2560 | 0 | |
| # C8 | RSH Resistance to Solder Heat JESD22-A111 260 °C ± 5 °C | 10 s | n.a. | n.a. | n.a. | |
| # C10 | SD Solderability J-STD-002 | | 37 | 1110 | 0 | |

[1] The physical limitations of Schottky diodes have to be considered (thermal runaway).

[2] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1)

Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Wafer Fab | Technology | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|------------------|------------|----------|---------|--------------------|------------|
| Nexperia DHAM | Schottky | 9320 | 0 | 0,46 | 2,19E+09 |

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